

01-06-2004

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To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document or copy thereof.

1. Name of conveying party:

a) Xiuhua Zhang

12-22-03

2. Name and address of receiving party:

a) Name: Lam Research Corporation

b) Address: 4650 Cushing Parkway, Fremont, CA 94538

3. Nature of conveyance

- | | | | |
|-------------------------------------|--------------------|--------------------------|-------------------|
| <input checked="" type="checkbox"/> | Assignment | <input type="checkbox"/> | Merger |
| <input type="checkbox"/> | Security Agreement | <input type="checkbox"/> | Change of Name |
| <input type="checkbox"/> | Other _____ | <input type="checkbox"/> | License Agreement |

Execution Date: a) 12/19/03

4. Application Number: Not yet assigned

The title of the new application is: CHEMICAL MECHANICAL PLANARIZATION (CMP) SYSTEM AND METHOD FOR PREPARING A WAFER IN A CLEANING MODULE

5. Please send all correspondence concerning this document to:

Michael K. Hsu, Esq.
 MARTINE & PENILLA, LLP
 710 Lakeway Drive, Suite 170
 Sunnyvale, CA 94085
Customer No. 25920
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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- Enclosed
 Any deficiency is authorized to be charged to Deposit Account No. 50-0805 (Order No. LAM2P456)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: December 22, 2003


 Michael K. Hsu, Esq.
 Registration No. 46,782

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40.00 DP

Attorney Docket No. LAM2P456

(Revised 01/96)

PATENT
REEL: 014847 FRAME: 0715

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

CHEMICAL MECHANICAL PLANARIZATION (CMP) SYSTEM AND METHOD FOR PREPARING A WAFER IN A CLEANING MODULE

(Atty. Docket No. LAM2P456) for which we have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventors hereby:

- 1) Sell, assign and transfer to Lam Research Corporation, a Delaware corporation having a place of business at 4650 Cushing Parkway, Fremont, CA 94538 U.S. (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

1) Signature: 
Typed Name: Xuhua Zhang

Date: 12/19/03

Attorney Docket No. LAM2P456